

Global Thermally Conductive Epoxy Die Attach Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Thermally Conductive Epoxy Die Attach market size was valued at US\$ 124 million in 2025 and is forecast to a readjusted size of US\$ 195 million by 2032 with a CAGR of 6.6% during review period.

Thermally conductive epoxy die attach adhesive is a functional bonding material used in the die attach step of semiconductor packaging. It uses epoxy resin as the matrix and incorporates silver, aluminum nitride, alumina, diamond, or composite ceramic fillers to improve heat transfer, forming a stable mechanical bond and a controlled thermal path between the die and the lead frame, ceramic substrate, PCB, package substrate, or heat dissipation structure. This material addresses issues such as junction temperature rise, excessive thermal resistance, thermal cycling failure, reduced damp-heat reliability, and bond-line voids in high-power-density devices, while enabling either electrically conductive and thermally conductive designs or electrically insulating and thermally conductive designs depending on package architecture. Common delivery forms include one-component heat-curing paste, two-component paste, premixed frozen adhesive, B-staged film, and materials designed for dispensing, pin transfer, screen printing, or wafer backside coating. Typical applications include power semiconductors, automotive power devices, LED and laser diodes, RF and microwave devices, optoelectronic devices, hybrid integrated circuits, and high-performance computing chip packaging. Key competitive factors include thermal conductivity, volume resistivity, ionic contamination, curing window, rheological stability, bond line thickness control, die shear strength, moisture absorption, and long-term thermal cycling reliability.

Thermally conductive epoxy die attach adhesive is at a critical stage in which

semiconductor packaging materials are evolving from general-purpose bonding materials into functional thermal management materials. As chip operating power, packaging density, and heat generation per unit area continue to rise, the die attach layer is no longer merely a bonding medium that supports the chip. It has become a core interface that determines junction temperature, thermal resistance, warpage, interfacial stress, and long-term reliability. Epoxy systems provide strong adhesion, formulation flexibility, damp-heat resistance, and process compatibility. By incorporating silver, aluminum nitride, alumina, diamond, and composite ceramic fillers, suppliers can achieve different levels of thermal conductivity and select either electrically conductive and thermally conductive designs or electrically insulating and thermally conductive designs depending on the device's electrical architecture. As packaging requirements rise for power semiconductors, automotive electronics, LEDs, laser diodes, RF devices, and high-performance computing chips, customer evaluation criteria are expanding beyond viscosity, curing time, and bond strength to include thermal conductivity, volume resistivity, bond line thickness, low voiding, low ionics, moisture absorption, thermal cycling life, and automated dispensing stability. This shift will continue to raise the technical threshold for high-end thermally conductive epoxy die attach adhesives and encourage suppliers to pursue deeper formulation customization around package structures, die sizes, and heat dissipation paths.

From the supply perspective, the market features parallel development by international leaders and regional substitution suppliers. European, American, and Japanese suppliers have accumulated long-standing expertise in high-reliability microelectronic packaging materials and generally offer more complete portfolios, reliability databases, and cross-regional customer qualification capabilities. Their product coverage includes conductive die attach adhesives, electrically insulating thermal adhesives, B-staged films, premixed frozen adhesives, wafer backside coating materials, and high-thermal-conductivity specialty materials. At the same time, suppliers in mainland China, Taiwan, and South Korea are accelerating adoption with local semiconductor assembly and test, LED, power module, and electronics manufacturing customers. Their advantages lie in service responsiveness, cost control, application validation support, and supply chain security. Because these materials typically require formulation screening, dispensing process window confirmation, curing profile matching, die shear testing, damp-heat reliability evaluation, thermal cycling, and end-customer qualification before volume production, competition is not driven by price alone. It is a combined contest of material performance, batch stability, process support capability, and customer qualification cycle. High-end applications are expected to remain led by companies with extensive application data and global customer resources, while mid-range and regional scenarios will continue to create substitution opportunities for local suppliers.

The long-term demand trend is clear. Semiconductor packaging is expanding from traditional consumer electronics into new energy vehicles, industrial control, energy conversion, AI servers, data centers, communication infrastructure, and high-reliability optoelectronic devices. This expansion is transforming die attach materials from ordinary bonding consumables into part of the package thermal path and reliability design. Power devices place particularly high requirements on thermal interfaces. SiC, GaN, IGBT, MOSFET, laser diode, and high-brightness LED devices face higher heat flux density and more severe thermal cycling, requiring thermally conductive epoxy die attach adhesives to balance thermal conductivity, low stress, low moisture absorption, and manufacturability. At the same time, packaging capacity is highly concentrated in Asia Pacific, where the regional manufacturing ecosystem is complete and customer validation and volume ramp-up can proceed quickly. This will continue to support demand in China, Japan, South Korea, Taiwan, and Southeast Asia. As automotive electronics and industrial power electronics impose stricter long-term reliability requirements, material suppliers will further enhance product value through high-thermal-conductivity filler hybridization, resin toughening, low-temperature rapid curing, low-ionic control, and automated dispensing compatibility.

This report is a detailed and comprehensive analysis for global Thermally Conductive Epoxy Die Attach market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Thermally Conductive Filler System and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Thermally Conductive Epoxy Die Attach market size and forecasts, in consumption value (\$ Million), sales quantity (Kilogram), and average selling prices (US\$/Kg), 2021-2032

Global Thermally Conductive Epoxy Die Attach market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (Kilogram), and average selling prices (US\$/Kg), 2021-2032

Global Thermally Conductive Epoxy Die Attach market size and forecasts, by Thermally

Conductive Filler System and by Application, in consumption value (\$ Million), sales quantity (Kilogram), and average selling prices (US\$/Kg), 2021-2032

Global Thermally Conductive Epoxy Die Attach market shares of main players, shipments in revenue (\$ Million), sales quantity (Kilogram), and ASP (US\$/Kg), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Thermally Conductive Epoxy Die Attach

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Thermally Conductive Epoxy Die Attach market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Henkel AG & Co. KGaA, NAMICS Corporation, Meridian Adhesives Group, Master Bond Inc., DELO Industrial Adhesives, Dr. H²nle AG, Polytec PT GmbH Polymere Technologien, Nan Pao Resins Chemical Co., Ltd., Darbond Technology Co., Ltd., KCC Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Thermally Conductive Epoxy Die Attach market is split by Thermally Conductive Filler System and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Thermally Conductive Filler System, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Thermally Conductive Filler System

Silver-Filled Thermally Conductive Epoxy Die Attach Adhesive

Aluminum Nitride-Filled Thermally Conductive Epoxy Die Attach Adhesive

Alumina-Filled Thermally Conductive Epoxy Die Attach Adhesive

Diamond-Filled Thermally Conductive Epoxy Die Attach Adhesive

Composite Ceramic-Filled Thermally Conductive Epoxy Die Attach Adhesive

Market segment by Delivery Form

Dispensing Paste Thermally Conductive Epoxy Die Attach Adhesive

Screen Printing Paste Thermally Conductive Epoxy Die Attach Adhesive

Premixed Frozen Thermally Conductive Epoxy Die Attach Adhesive

B-Stage Film Thermally Conductive Epoxy Die Attach Adhesive

Market segment by Curing Process

Heat-Curing Thermally Conductive Epoxy Die Attach Adhesive

Fast Heat-Curing Thermally Conductive Epoxy Die Attach Adhesive

Low-Temperature Heat-Curing Thermally Conductive Epoxy Die Attach Adhesive

Other

Market segment by Die Attach Process

Dispensing-Applied Thermally Conductive Epoxy Die Attach Adhesive

Pin-Transfer-Applied Thermally Conductive Epoxy Die Attach Adhesive

Screen-Printing-Applied Thermally Conductive Epoxy Die Attach Adhesive

Wafer-Backside-Coated Thermally Conductive Epoxy Die Attach Adhesive

Market segment by Application

Power Semiconductor Packaging

Automotive Power Device Packaging

LED and Laser Diode Packaging

Optoelectronic Device Packaging

High-Performance Computing Chip Packaging

Major players covered

Henkel AG & Co. KGaA

NAMICS Corporation

Meridian Adhesives Group

Master Bond Inc.

DELO Industrial Adhesives

Dr. H²nle AG

Polytec PT GmbH Polymere Technologien

Nan Pao Resins Chemical Co., Ltd.

Darbond Technology Co., Ltd.

KCC Corporation

Tanaka Precious Metals

Qnity Electronics

AI Technology, Inc.

Creative Materials Inc.

Vitrochem Technology

LIPOLY

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Thermally Conductive Epoxy Die Attach product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Thermally Conductive Epoxy Die Attach, with price, sales quantity, revenue, and global market share of Thermally Conductive Epoxy Die Attach from 2021 to 2026.

Chapter 3, the Thermally Conductive Epoxy Die Attach competitive situation,

sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Thermally Conductive Epoxy Die Attach breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Thermally Conductive Filler System and by Application, with sales market share and growth rate by Thermally Conductive Filler System, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026. and Thermally Conductive Epoxy Die Attach market forecast, by regions, by Thermally Conductive Filler System, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Thermally Conductive Epoxy Die Attach.

Chapter 14 and 15, to describe Thermally Conductive Epoxy Die Attach sales channel, distributors, customers, research findings and conclusion.

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